

CBR-SMD RF COG, Ceramic, 2.3 pF, +/-0.1 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



| Dimensions | |
|------------|-----------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.1mm |
| W | 0.8mm +/-0.1mm |
| T | 0.8mm +/-0.07mm |
| B | 0.4mm +/-0.15mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging: | T&R, 180mm, Plastic Tape |
| Packaging Quantity: | 4000 |

| General Information | |
|---------------------|--|
| Series: | CBR-SMD RF COG |
| Style: | SMD Chip |
| Description: | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features: | Ultra High Q, Low ESR, Class I |
| RoHS: | Yes |
| Termination: | Tin |
| Marking: | No |
| AEC-Q200: | No |
| Notes: | Solder Wave or Solder Reflow. |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

| Specifications | |
|----------------------------------|---------------------|
| Capacitance: | 2.3 pF |
| Capacitance Tolerance: | +/-0.1 pF |
| Voltage DC: | 50 VDC |
| Dielectric Withstanding Voltage: | 125 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Dissipation Factor: | 0.224% |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 10 GOhms |
| Quality Factor: | 446 |

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